

In the specification:

Please replace the paragraphs starting on page 17, line 6 and ending on page 18, line 3 with the following paragraphs:

More specifically, as shown on the left-hand side in Figure 9, an FPC module 900 is shown having a cap 901, a die 902 having, respectively, on first and second sides an adhesive or thermal compound 903 and interconnection array 904, optionally with an underfill 904, a substrate 905 coupled, via a Sylgard 577 ® seal 906 to the cap with the die 902 therebetween, a socket 907 coupled to an underside of the substrate 905, a card (printed circuit board) 908 coupled to the substrate with the socket therebetween, and a steel stiffener 909 coupled to the underside of the card 908. Engagement posts 910 and engagement spring (not shown) are also provided for applying LGA engagement load to the assembly.

As shown on the right-hand side in Figure 9, an ATI module 950 is shown having a cap 951, a thermal spreader 958 having an adhesive or thermal compound 953 formed between the underside of the cap and the thermal spreader, a die 952 having, respectively, on first and second sides an adhesive thermal interface (ATI) 959 and interconnection array 954, optionally with an underfill 954, a substrate 955 coupled to the cap with the die 952 therebetween, a substrate 955 coupled, via a Sylgard 577® seal 956 to the cap with the die 952 therebetween a socket 957 coupled to an underside of the substrate 955, a card (printed circuit board) 958A coupled to the

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substrate with the socket therebetween, and a steel stiffener ~~959~~ 961 coupled to the underside of the card 958A. Engagement posts 960 and engagement spring (not shown) are also provided for applying LGA engagement load to the assembly. As is evident from Figure 9, the ATI module differs mainly from the FPC module by the addition of the thermal spreader 958 and the ATI 959 formed at the interface of the die 952 and the thermal spreader 958.